

Title (en)

HIGH DENSITY TUNGSTEN MATERIAL SINTERED AT LOW TEMPERATURE

Title (de)

HOCHDICHTES, BEI NIEDRIGEN TEMPERATUREN GESINTERTES MATERIAL AUS WOLFRAM

Title (fr)

MATERIAU TUNGSTENE A HAUTE DENSITE FRITTE A BASSE TEMPERATURE

Publication

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Application

**EP 00953219 A 20000615**

Priority

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- FR 9908186 A 19990625

Abstract (en)

[origin: WO0100892A1] The invention concerns a tungsten-based sintered material, with relative mean density higher than 93 % and HV0.3 hardness  $\geq 400$ . It comprises: tungsten having a purity higher than 99.9 %, an additive consisting of nickel and/or cobalt powder in a mass percentage not more than 0.08 %, an average particle size of tungsten grains of equiaxial shape ranging between 2 and 40  $\mu\text{m}$  and uniformly distributed for a given average size; and uniformly distributed residual porosity with less than 85 % of the population of pores having a unit volume less than 4  $\mu\text{m}^3$ .

IPC 1-7

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